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# FGA180N33AT 330V, 180A PDP Trench IGBT

### Features

- High Current Capability
- Low saturation voltage: V<sub>CE(sat)</sub> =1.03V @ I<sub>C</sub> = 40A
- High input impedance
- RoHS compliant

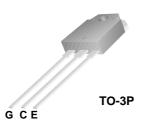
## Applications

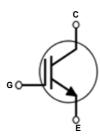
PDP SYSTEM



# **General Description**

Using Novel Trench IGBT Technology, Fairchild's new series of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.





### **Absolute Maximum Ratings**

Symbol	· ·		Ratings	Units V	
V <sub>CES</sub>			330		
V <sub>GES</sub>	Gate to Emitter Voltage		$\pm 30$	V	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	180	А	
I <sub>C pulse (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C	450	А	
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	390	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100 <sup>o</sup> C	156	W	
TJ	Operating Junction Temperature		-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
Τ <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

#### Notes:

1: Repetitive test, pulse width = 100usec, Duty = 0.1

\* I<sub>C</sub> pulse limited by max Tj

# **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$ (IGBT)	HeJC(IGBT) Thermal Resistance, Junction to Case		0.32	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

April 2008

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Device N	larking	Device	Packag	ackage Type		er Tube	B	ox
FGA180N33AT FGA180N33ATTU		TO-3P	TO-3P Tube		30ea		-	
Electric Symbol	al Cha	Parameter	1	T <sub>C</sub> = 25°C unless otherwise noted Test Conditions	Min.	Тур.	Max.	Units
Symbol		i arameter				iyp.	Wax.	Units
Off Charac	teristics							
BV <sub>CES</sub>	Collector	to Emitter Breakdown V	oltage V <sub>GE</sub> =	0V, I <sub>C</sub> = 250μA	330	-	-	V
I <sub>CES</sub>	Collector	Cut-Off Current	$V_{CE} =$	$V_{CES}, V_{GE} = 0V$	-	-	250	μΑ
I <sub>GES</sub>	G-E Leakage Current		V <sub>GE</sub> =	$V_{GES}$ , $V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics							
V <sub>GE(th)</sub>	G-E Thre	shold Voltage	I <sub>C</sub> = 25	50uA, V <sub>CE</sub> = V <sub>GE</sub>	2.5	4.0	5.5	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage			0A, V <sub>GE</sub> = 15V	-	1.1	1.4	V
			I <sub>C</sub> = 18	I <sub>C</sub> = 180A, V <sub>GE</sub> = 15V,		1.68	-	V
• CE(sat)			I <sub>C</sub> = 18	$I_{C} = 180A, V_{GE} = 15V$ $T_{C} = 125^{\circ}C$		1.89	_	V
Dynamic C	haracteris	tics						
C <sub>ies</sub>	Input Cap				-	3880	-	pF
C <sub>oes</sub>		t Capacitance		V <sub>CE</sub> = 30V, V <sub>GE</sub> = 0V, f = 1MHz		305	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance		f = 110			180	-	pF
Switching	Character	istics						
t <sub>d(on)</sub>	1	Delay Time			-	27	-	ns
t <sub>r</sub>	Rise Time		V <sub>CC</sub> =	200V, $I_C = 40A$ ,	-	80	-	ns
t <sub>d(off)</sub>	Turn-Off	Delay Time		$= R_G = 5\Omega, V_{GE} = 15V,$ Resistive Load, $T_C = 25^{\circ}C$		108	-	ns
t <sub>f</sub>	Fall Time				-	180	240	ns
t <sub>d(on)</sub>	Turn-On I	Delay Time			-	26	-	ns
t <sub>r</sub>	Rise Time	e	V <sub>CC</sub> =	$V_{CC} = 200V, I_C = 40A,$ $R_G = 5\Omega, V_{GE} = 15V,$ Resistive Load, $T_C = 125^{\circ}C$		75	-	ns
t <sub>d(off)</sub>	Turn-Off I	Delay Time	Resist			112	-	ns
t <sub>f</sub>	Fall Time			-	-	250	300	ns
Qg	Total Gate	e Charge			-	169	-	nC
Q <sub>ge</sub>	Gate to E	mitter Charge		200V, I <sub>C</sub> = 40A,	-	22	-	nC
Q <sub>gc</sub>	Gate to C	ollector Charge	V <sub>GE</sub> = 15V		-	69	-	nC

# **Typical Performance Characteristics**



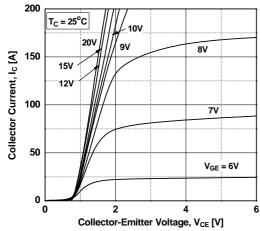


Figure 3. Typical Saturation Voltage Characteristics

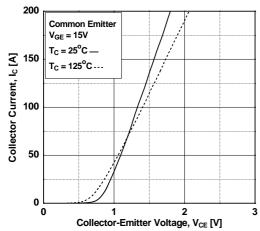


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

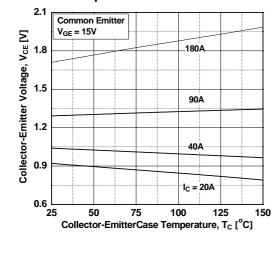


Figure 2. Typical Output Characteristics

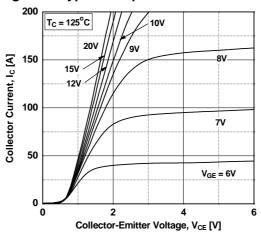


Figure 4. Transfer Characteristics

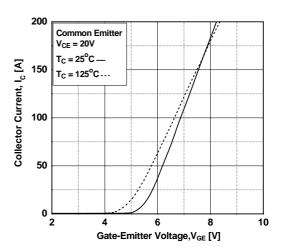
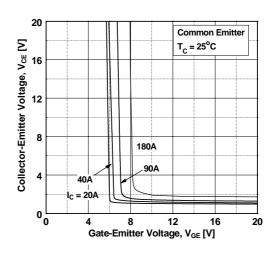


Figure 6. Saturation Voltage vs. V<sub>GE</sub>



# **Typical Performance Characteristics**



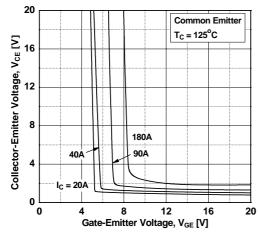
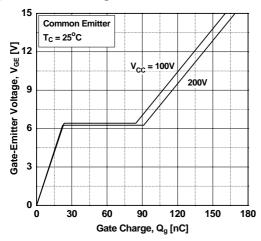


Figure 9. Gate charge Characteristics





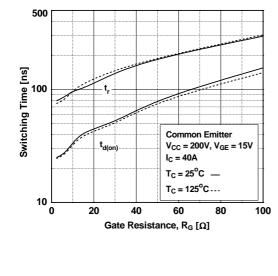


Figure 8. Capacitance Characteristics

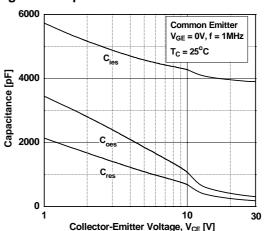


Figure 10. SOA Characteristics

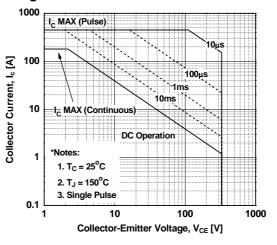
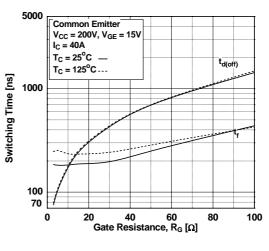


Figure 12. Turn-off Characteristics vs. Gate Resistance



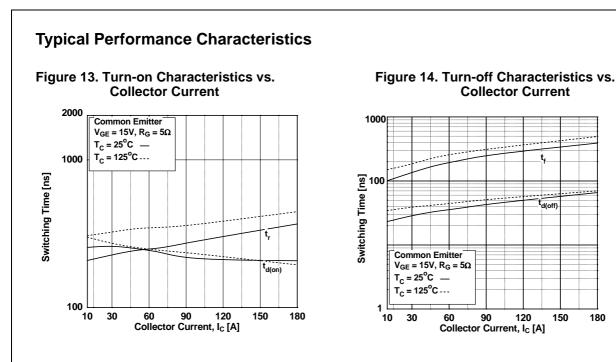
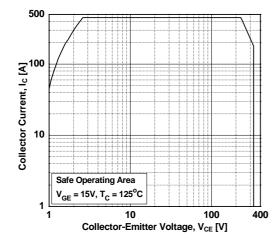
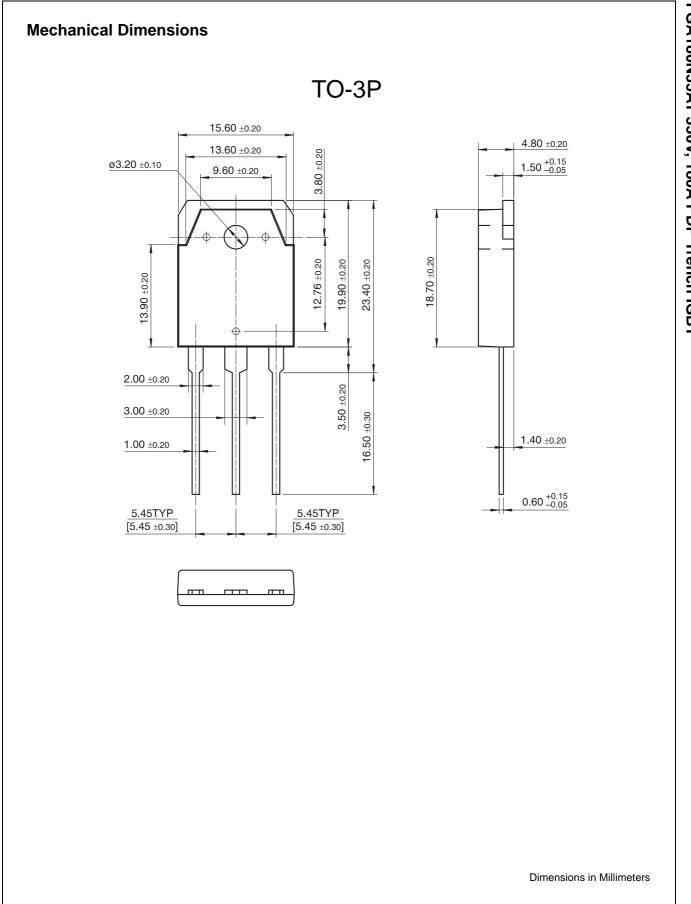


Figure 15. Turn off Switching SOA Characteristics



### **Typical Performance Characteristics** Figure 16. Transient Thermal Impedance of IGBT 1 Thermal Response [Zthjc] 0.5 0.1 0.2 0.1 0.05 0.02 0.01 0.01 single pulse Duty Factor, D = t1/t2 Peak T<sub>i</sub> = Pdm x Zthjc + T<sub>C</sub> 1E-3 -1E-5 1E-4 1E-3 0.01 0.1 1 Rectangular Pulse Duration [sec]





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